

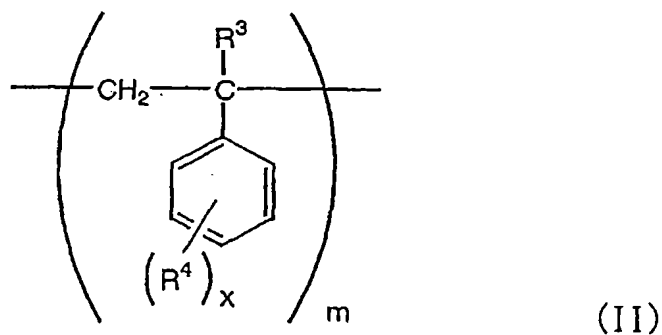
I. AMENDMENT TO THE CLAIMS:

Kindly amend claims 2, and add new claims 13-16 as follows.

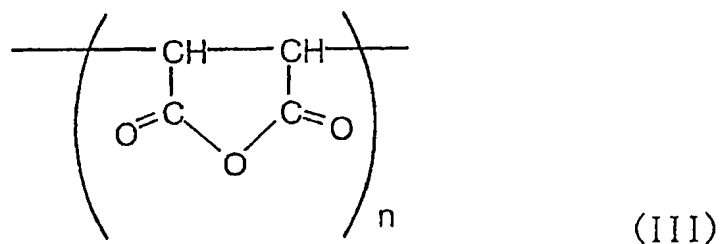
The present claims will replace all prior versions of claims in the present application.

LISTING OF THE CLAIMS:

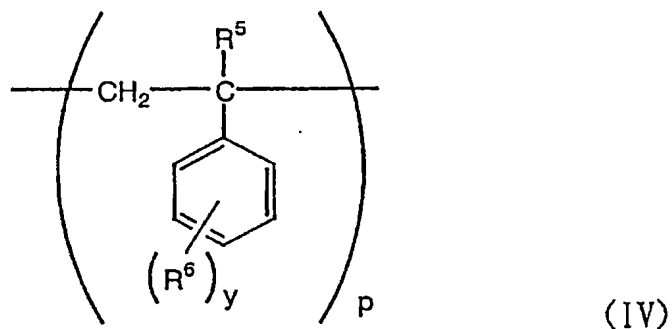
1. (Previously Presented) A thermosetting resin composition comprising:
 - (1) a metal salt of a disubstituted phosphinic acid, and
 - (2) a resin having a dielectric constant of 2.9 or less at a frequency of 1 GHz or more.
2. (Currently Amended) The thermosetting ~~resin~~^{resin} composition according to claim 1, wherein the dielectric constant of the thermosetting resin composition is 3.0 or less at a frequency of 1 GHz or more.
3. (Previously Presented) The thermosetting resin composition according to claim 1, which further comprises (3) a thermosetting nitrogen atom-containing resin.
4. (Previously Presented) The thermosetting resin composition according to claim 1, wherein the component (2) is at least one resin compositions selected from the group consisting of:
copolymer resin (2-1) comprising:
monomer unit (a) represented by formula (II):



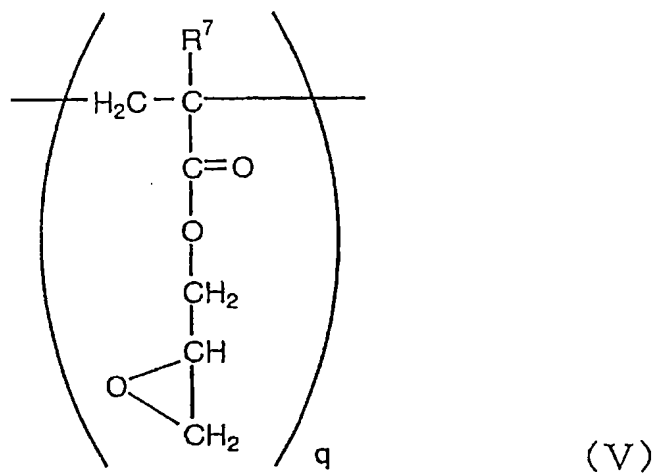
wherein R^3 is a hydrogen atom, a halogen atom or a hydrocarbon group having 1 to 5 carbon atoms; R^4 s are each independently a halogen atom, an aliphatic hydrocarbon group having 1 to 5 carbon atoms, an aromatic hydrocarbon group or a hydroxyl group; x is an integer of 0 to 3; and m is a natural number representing the repeating number of a monomer unit in a copolymer, and monomer unit (b) represented by formula (III):



wherein n is a natural number representing the repeating number of a monomer unit in a copolymer;
copolymer resin (2-2) comprising:
monomer unit (c) represented by formula (IV):

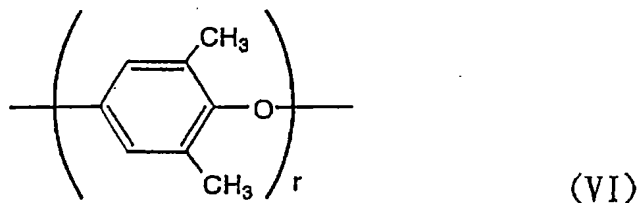


wherein R^5 is a hydrogen atom, a halogen atom or a hydrocarbon group having 1 to 5 carbon atoms; R^6 s are each independently a halogen atom, an aliphatic hydrocarbon group having 1 to 5 carbon atoms, an aromatic hydrocarbon group or a hydroxyl group; y is an integer of 0 to 3; and p is a natural number representing the repeating number of a monomer unit in a copolymer, and monomer unit (d) represented by formula (V):



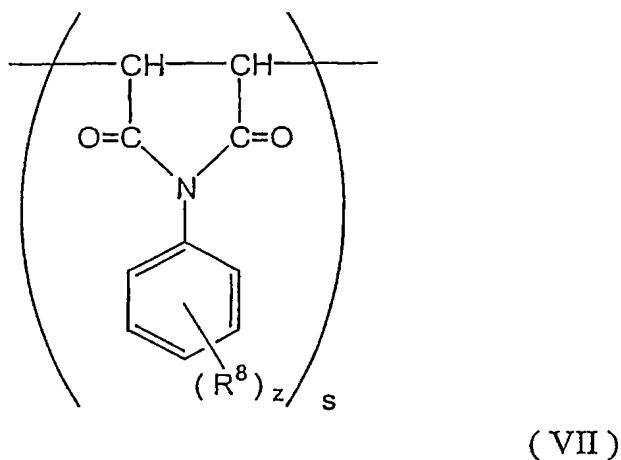
wherein R^7 is a hydrogen atom, a halogen atom or a hydrocarbon group having 1 to 5 carbon atoms; and q is a natural number representing the repeating number of a monomer unit in a copolymer; and resin (2-3) comprising:

monomer unit (e) represented by formula (VI):



wherein r is a natural number representing the repeating number of a monomer unit in a copolymer.

5. (Previously Presented) The thermosetting resin composition according to claim 4, wherein the copolymer resin (2-1) is a copolymer resin further comprising:
monomer unit (f) represented by the following formula (VII):



wherein R^8 is a halogen atom, an aliphatic hydrocarbon group having 1 to 5 carbon atoms, an aromatic hydrocarbon group, a hydroxyl group, a thiol group or a carboxyl group; z is an integer of 0 to 3; and s is a natural number representing the repeating number of a monomer unit in a copolymer.

6. (Previously Presented) The thermosetting resin composition according to claim 1, which further comprises (4) an epoxy resin.

7. (Previously Presented) A prepreg using the thermosetting resin composition according to claim 1.

8. (Previously Presented) A laminated board obtained by using and laminate molding the prepreg according to claim 7.

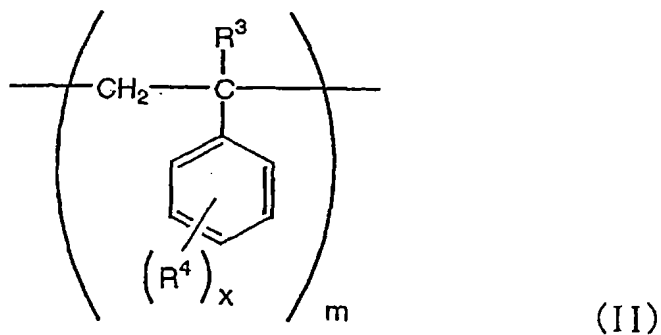
9. (Previously Presented) A thermosetting resin composition comprising a metal salt of a disubstituted phosphinic acid, wherein a dielectric constant of the composition is 3.0 or less at a frequency of 1 GHz or more.

10. (Previously Presented) The thermosetting resin composition according to claim 2, which further comprises (3) a thermosetting nitrogen atom-containing resin.

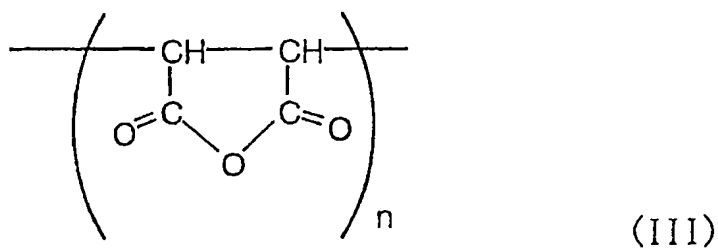
11. (Previously Presented) The thermosetting resin composition according to claim 2, wherein the component (2) is at least one resin compositions selected from the group consisting of:

copolymer resin (2-1) comprising:

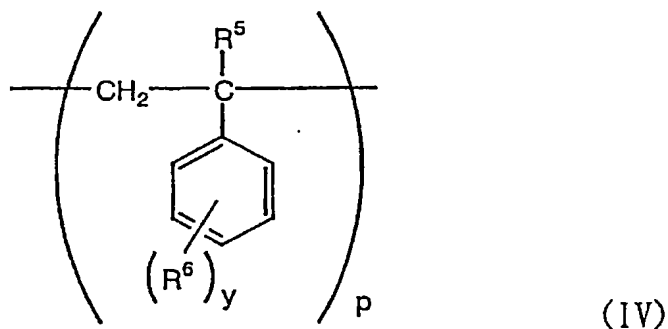
monomer unit (a) represented by formula (II):



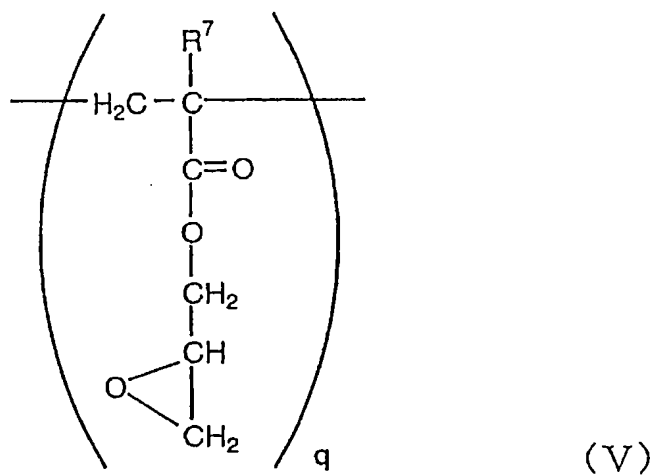
wherein R^3 is a hydrogen atom, a halogen atom or a hydrocarbon group having 1 to 5 carbon atoms; R^4 's are each independently a halogen atom, an aliphatic hydrocarbon group having 1 to 5 carbon atoms, an aromatic hydrocarbon group or a hydroxyl group; x is an integer of 0 to 3; and m is a natural number representing the repeating number of a monomer unit in a copolymer, and monomer unit (b) represented by formula (III):



wherein n is a natural number representing the repeating number of a monomer unit in a copolymer;
copolymer resin (2-2) comprising:
monomer unit (c) represented by formula (IV):

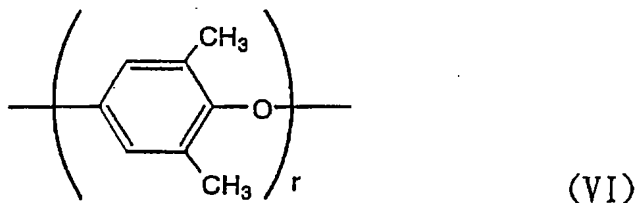


wherein R^5 is a hydrogen atom, a halogen atom or a hydrocarbon group having 1 to 5 carbon atoms; R^6 s are each independently a halogen atom, an aliphatic hydrocarbon group having 1 to 5 carbon atoms, an aromatic hydrocarbon group or a hydroxyl group; y is an integer of 0 to 3; and p is a natural number and representing the repeating number of a monomer unit in a copolymer, and monomer unit (d) represented by formula (V):



wherein R^7 is a hydrogen atom, a halogen atom or a hydrocarbon group having 1 to 5 carbon atoms; and q is a natural number representing the repeating number of a monomer unit in a copolymer; and resin (2-3) comprising:

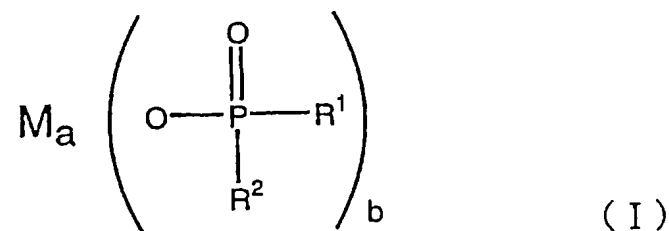
monomer unit (e) represented by formula (VI):



wherein r is a natural number representing the repeating number of a monomer unit in a copolymer.

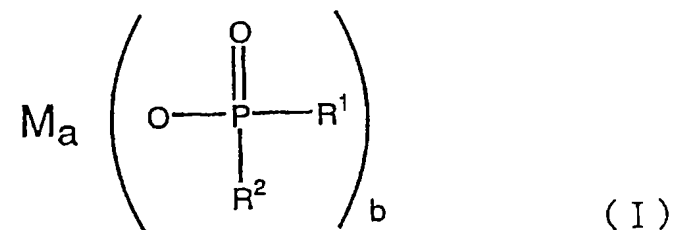
12. (Previously Presented) The thermosetting resin composition according to claim 2, which further comprises (4) an epoxy resin.

13. (NEW) The thermosetting resin composition according to claim 1, wherein the metal salt of the disubstituted phosphinic acid is represented by formula (I):



wherein R^1 and R^2 are each independently an aliphatic hydrocarbon group having 1 to 5 carbon atoms or an aromatic hydrocarbon group; a and b are each an integer of 1 to 9; and M is one metal selected from Li, Na, K, Mg, Ca, Sr, Ba, Al, Ge, Sn, Sb, Bi, Zn, Ti, Zr, Mn, Fe and Ce.

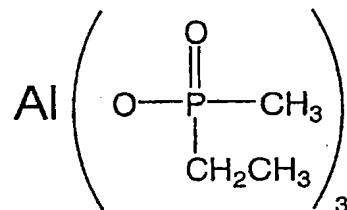
14. (NEW) The thermosetting resin composition according to claim 9, wherein the metal salt of the disubstituted phosphinic acid is represented by formula (I):



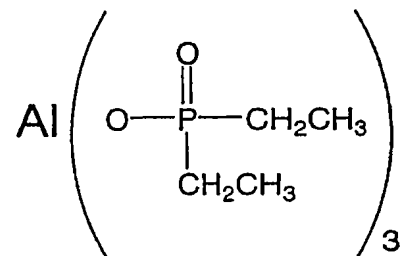
wherein R^1 and R^2 are each independently an aliphatic hydrocarbon group having 1 to 5 carbon atoms or an aromatic hydrocarbon group; a and b are each an integer of 1 to 9; and M is one metal selected from Li, Na, K, Mg, Ca, Sr, Ba, Al, Ge, Sn, Sb, Bi, Zn, Ti, Zr, Mn, Fe and Ce.

15. (NEW) The thermosetting resin composition according to claim 1, wherein the metal salt of the disubstituted phosphinic acid is selected from the group consisting of

(1-1) Aluminum salt of methyl ethyl phosphinate

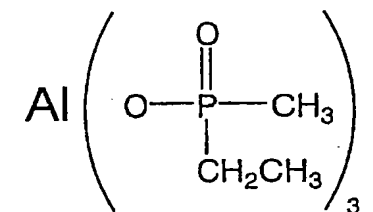


and (1-2) Aluminum salt of diethyl phosphinate



16. (NEW) The thermosetting resin composition according to claim 9, wherein the metal salt of the disubstituted phosphinic acid is selected from the group consisting of

(1-1) Aluminum salt of methyl ethyl phosphinate



and (1-2) Aluminum salt of diethyl phosphinate

